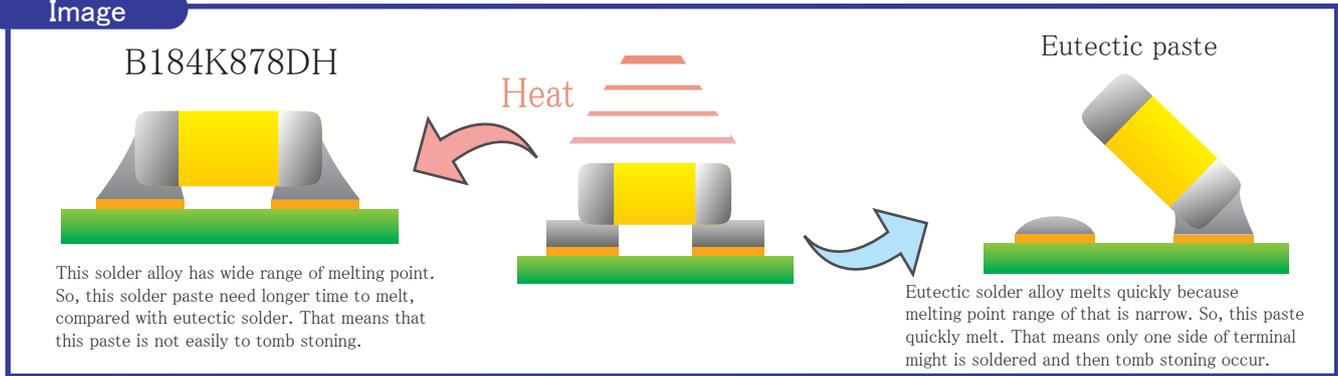


SOLDIM B184K878DH

- This product has good wettability because solder powder isn't easily oxidized.
- This solder alloy has wide range of melting point, compared with eutectic solder. So, Tomb stoning phenomenon doesn't occur using this solderpaste.
- High electric reliability based on new activator technology of this flux.

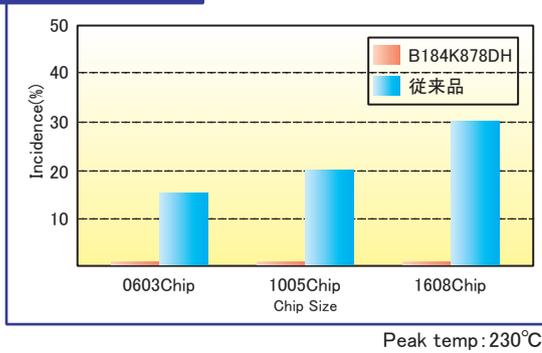
Image



Tomb stoning test

This product has less tomb stoning.

Tomb stoning Test



Wetting test

This product has good wettability.

0.5pitchQFP

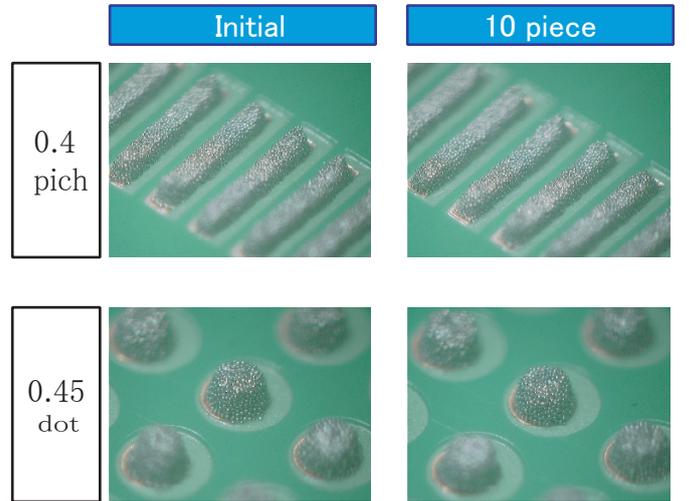


1005Chip



Printing test

This product has good printability.

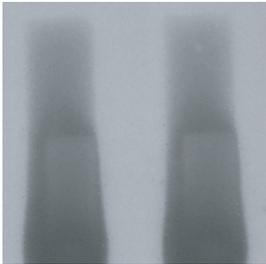


Condition Velocity: 30mm/s

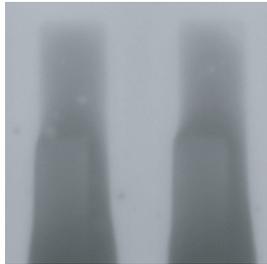
Void test

This product has less void.

B184K878DH



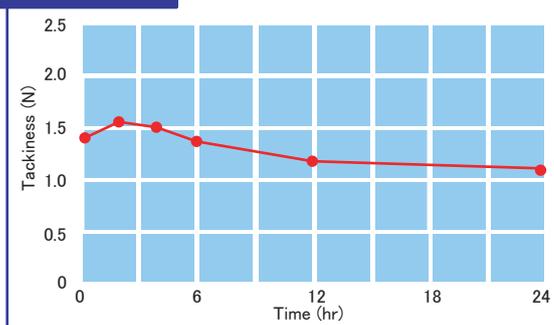
Conventional product



Tackiness Test

Tackiness of this product is stable over long time.

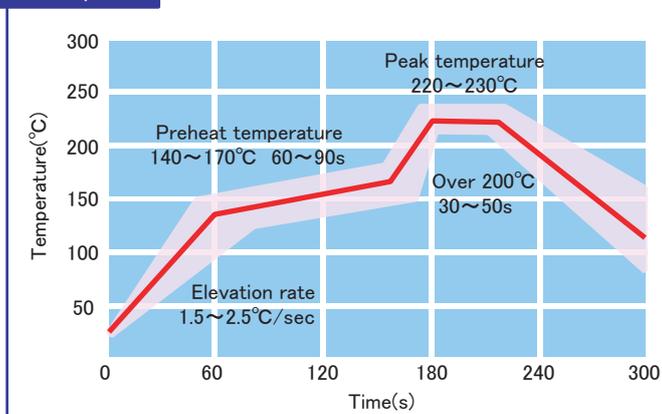
Tackiness Test



Test condition: 25°C

Recommendable temperature profile

Reflow profile



Characteristic Data

Characteristic data of B184K878DH is shown below.

Product name	B184K878DH
Alloy composition(%)	Sn:62, Ag:0.4, Pb:Balance
Melting point(°C)	179~184
Powder particle size(μm)	38~25
Halide content(%)	0.14※ ₁
Flux contents(%)	9.8
Spreading ratio(%)	93
Copper plate corrosion test	Pass
Insulation resistance test(Ω)	≥5.0x10 ⁸
Viscosity(Pa·s)	200
Thixotropy index	0.57
Tackiness test	>24Hr
Storage stability	6 months (Under 10°C)

※ Above values are typical value.

※₁ This solder paste contain non-ionic halide activator.

Precautions

- Please keep solder paste in cold storage such as 0 to 10°C. If it is left in hot condition, it may cause changing of Viscosity or hygroscopic inferior.
- Please restore the temperature of paste to room condition ahead of using.(It is required about three hours)
- Please stir the solder paste homogeneously by mixer before using.(We suggest the mixing time at 90sec. by Japan Unix machine, or at 10 minutes by Malcom machine.)
- Please do not mix used solder paste with virgin paste.
- Please close up the opened bottle of solder paste to restore in refrigerator.
- After printing, please re-flow the solder paste as soon as possible.
- Please choose the suitable re-flow condition which meets to the solder paste. The flux happens to carbonization by unsuitable re-flow condition, also it is no good for insulation resistance. The profile is different because it depend on thermal capacity of chips and board, you should consider enough to determine the profile.
- Please do not touch the paste by bare-handed and inhale the gas by soldering.

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